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Materials Declaration Form


IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
* : Required Field			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-11-12
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Floriana San Biagio	Representative Title	AMS Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement	
<p>While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.</p>	
Legal Statement	
Supplier Acceptance *	true
Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	ANDP*XLAA50J	A	Z7GA	2015-11-12
Amount	UoM	Unit type	ST ECOPACK Grade	
5.26	mg	Each	ECOPACK® 2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFN	2x2x0.5	6	No lead	
Comment	Package: A0BU UDFN/COL 2X2X0.5 6L PITCH 0.65; MDF valid for STTS751-ODP3F			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	ANDP*XLAA5QJ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.43	mg	supplier	die	Silicon (Si)	7440-21-3		0.396	mg	920930	75285
Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	11628	951
Die				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	2326	190
Die				supplier	metallization	Tungsten (W)	7440-33-7		0.007	mg	16279	1331
Die				supplier	passivation	Silicon Nitride (SiN)	12033-89-5		0.002	mg	4651	380
Die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.019	mg	44186	3612
Leadframe	Copper & its alloys	1.313	mg	supplier	alloy	Copper (Cu)	7440-50-8		1.235	mg	940594	234791
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.054	mg	41127	10266
Leadframe				supplier	alloy	Chromium (Cr)	7440-47-3		0.003	mg	2285	570
Leadframe				supplier	alloy	Ti (Sn)	7440-31-5		0.003	mg	2285	570
Leadframe	Nickel (Ni)			supplier	metallization	Nickel (Ni)	7440-02-0		0.016	mg	12186	3042
Leadframe	Precious metals			supplier	metallization	Palladium (Pd)	7440-05-3		0.001	mg	762	190
Leadframe	Precious metals			supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	762	190
Die attach	Other Organic Materials	0.112	mg	supplier	Glue	Aluminum oxide	1344-28-1		0.039	mg	348214	7414
Die attach				supplier	Glue	Diethylene glycol monoethyl ether acetate	112-15-2		0.034	mg	303571	6464
Die attach				supplier	Glue	Epoxy resin	Proprietary		0.033	mg	294643	6274
Die attach				supplier	Glue	Amine	Proprietary		0.006	mg	53571	1141
Bonding wire	Precious metals	0.039	mg	supplier	wire	Gold (Au)	7440-57-5		0.039	mg	1000000	7414
Encapsulation	Other Organic Materials	3.366	mg	supplier	mold compound	Silica fused	60676-86-0		3.047	mg	905229	579278
Encapsulation				supplier	mold compound	Epoxy resin	Proprietary		0.158	mg	46940	30038
Encapsulation				supplier	mold compound	Phenol resin	Proprietary		0.158	mg	46940	30038
Encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.003	mg	891	570